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# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

# **CONVEYING PARTY DATA**

Name	Execution Date
Katsuhiko Mochiduki	09/13/2007
Takaaki Mihara	09/13/2007

# **RECEIVING PARTY DATA**

Name:	Toray Industries, Inc.	
Street Address:	1-1 Nihonbashi-Muromachi 2-chome	
Internal Address:	Chuo-ku	
City:	Tokyo	
State/Country:	JAPAN	
Postal Code:	103-8666	

#### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11887283

#### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER: TIP-07-1400 308877-214

NAME OF SUBMITTER: Carol Coney

Total Attachments: 1

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### ASSIGNMENT

WHEREAS, We, Katsuhiko Mochiduki, and Takaaki Mihara, citizens of Japan, residing at Toray-Yoroizaka Apartment D-73, 12-3, Bunkyo-cho 2-chome, Mishima-shi, Shizuoka, 411-0033 Japan and Toray-Kamiiwasaki Apartment 4-6, 21-35, Bunkyo-cho 2-chome, Mishima-shi, Shizuoka, 411-0033 Japan, respectively, (hereinafter referred to as 'the undersigned"), having made an invention entitled Resin Composition. Molded Article And <u>Production Method Thereof</u> for which on the date set forth below, unless otherwise indicated here, undersigned executed an application for United States Letters Patent,

WHEREAS, Toray Industries, Inc., a corporation of Japan, with offices at 1-1 Nihonbashi-Muromachi 2-chome, Chuo-ku, Tokyo, 103-8666 Japan (hereinafter referred to as 'assignee"), is desirous of acquiring the entire right, title and interest in said invention, said application and all letters patent issuing for said invention,

NOW, THEREFORE, in consideration of One Dollar(\$1.00) and of other good and valuable consideration, receipt of which is hereby acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee the entire right, title and interest, for the United States of America, its territories and possessions, and for all foreign countries, in said invention, including said patent application, all divisions and continuations thereof, all rights to claim priority based thereon, all rights to file foreign applications on said invention, and all letters patent and reissues thereof, issuing for said invention in the United States of America and in any and all foreign countries.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the undersigned has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the assignee, and to execute all instruments proper to carry out the intent of this instrument. If the undersigned includes more than one individual, these obligations shall apply to all of the undersigned both individually and collectively.

The rights and property herein conveyed by the undersigned are free and clear of any encumbrance.

EXECUTED on September 13, 2007

Katsuhiko Mochiduki

Katsuhiko Mochiduki

Takaaki Mihara Takaaki Mihara

**RECORDED: 10/10/2007** 

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